## PATENT ASSIGNMENT

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RECORDATION FORM COVER SHEET PATENTS ONLY						
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.						
1. Name of conveying party(ies) Sung-Jun KIM Chang-Min HONG	2. Name and address of receiving party(ies) Name: Cheil Industries Inc.					
Additional name(s) of conveying party(ies) attached? Yes X No 3. Nature of conveyance/Execution Date(s): Execution Date(s) December 10, 2009 X Assignment Merger Security Agreement Change of Name Joint Research Agreement Government Interest Assignment Executive Order 9424, Confirmatory License Other	Street Address: 290 Gongdan-dong City: <u>Gumi-si</u> State: <u>Gyeongsangbuk-do</u> Country: <u>South Korea</u> <sub>Zip:</sub> 730-710 Additional name(s) & address(es) attached? Yes X No					
A. Patent Application No.(s) 12/634,768 Additional numbers at	document is being filed together with a new application. B. Patent No.(s)					
5. Name and address to whom correspondence concerning document should be mailed: Name: Summa, Additon & Ashe, P.A.	6. Total number of applications and patents involved: <u>1</u> 7. Total fee (37 CER 1 21(h) & 3 41) \$ 40.00					
Internal Address:	<ul> <li>7. Total fee (37 CFR 1.21(h) &amp; 3.41) \$_40.00</li> <li>Authorized to be charged by credit card</li> <li>Authorized to be charged to deposit account</li> </ul>					
Street Address: 11610 N. Community House Road, Suite 200	Enclosed None required (government interest not affecting title)					
City: Charlotte	8. Payment Information					
State: NCZip: 28277-2199	a. Credit Card Last 4 Numbers Expiration Date					
Phone Number: 704-945-6700 Fax Number: 704-945-6735 Email Address:	b. Deposit Account Number Authorized User Name					
9. Signature: /Melissa B. Pendleton/	 December 10, 2009					
Signature Melissa B. Pendleton Name of Person Signing	Total number of pages including cover 4					

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to: Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

#### ASSIGNMENT

WHEREAS, I, Sung-Jun KIM, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; and Chang-Min HONG, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in EMI/RFI Shielding Resin Composite Material and Molded Product Made Using the Same, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from Korean Application No. 10-2008-0125407, filed December 10, 2008, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Cheil Industries Inc., a Korean corporation, having a principal place of business at 290 Gongdan-dong, Gumi-si, Gyeongsangbuk-do, 730-710, Republic of Korea, (hereinafter referred to as "ASSIGNEE") has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned,

> PATENT REEL: 023632 FRAME: 0649

transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest-and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest-in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said

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INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

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IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

Dec. 10,	2009'	Sung-Jun KIM
Dec. 10	2009	Chang-Min HONG

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